



Material Content Data Sheet



Sales Product Name		IPD90N06S4-07		Issued		25. September 2017		
MA#		MA001055100						
Package		PG-TO252-3-11		Weight*		370.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.466	0.66	0.66	6649	6649
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		581	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	copper	7440-50-8	215.017	57.98	58.06	579763	580518
wire	non noble metal	aluminium	7429-90-5	4.075	1.10	1.10	10987	10987
encapsulation	organic material	carbon black	1333-86-4	1.236	0.33		3333	
	plastics	epoxy resin	-	21.629	5.83		58319	
	inorganic material	silicondioxide	60676-86-0	100.728	27.16	33.32	271600	333252
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10085	10085
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246
solder	noble metal	silver	7440-22-4	0.060	0.02		162	
	non noble metal	tin	7440-31-5	0.048	0.01		130	
	non noble metal	lead	7439-92-1	2.297	0.62	0.65	6194	6486
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51709	51777
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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